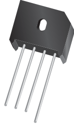
Material Composition Specification

CASE DM



Device average mass . . . . 7.5 g

Fluctuation margin . . . . +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	0.56%	42.08	Si	7440-21-3	0.56%	42	5,600
				Au	7440-57-5	0%	0.08	11
leadframe	copper	37.89%	2,842	Cu	7440-50-8	37.89%	2,842	378,929
die attach	high temperature solder	0.48%	36.006	Pb	7439-92-1	0%	0.006	1
				Sn	7440-31-5	0.48%	36	4,800
encapsulation	EMC	59.47%	4,460	epoxy resin	Proprietary	59.47%	4,460	594,660
plating*	tin/lead process	1.6%	120	Sn	7440-31-5	1.28%	96	12,800
				Pb	7439-92-1	0.32%	24	3,200
	matte tin	1.6%	120	Sn	7440-31-5	1.6%	120	16,000

*For Lead Free plating, add suffix “PB FREE” to part number.
For Tin/Lead plating, add suffix “TIN/LEAD” to part number.
No suffix designation allows for the supply of either lead-free or tin/lead plated product depending on availability.

Disclaimer
The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.